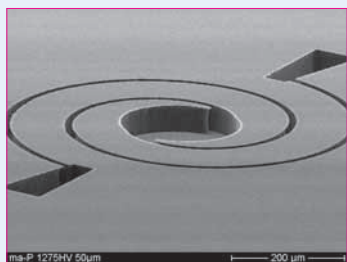
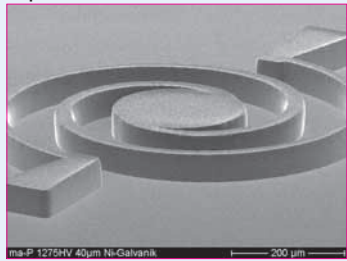


ma-P 1275 and ma-P 1275 HV – Positive Tone Photoresists

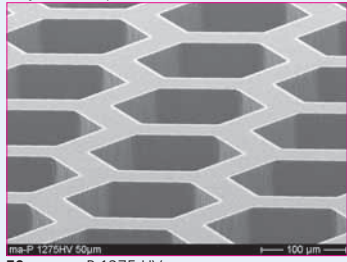
Versatile high viscosity positive tone photoresists for microsystems technology



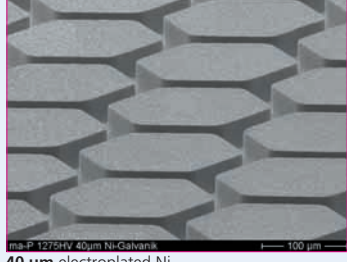
50 µm ma-P 1275 HV



40 µm electroplated Ni



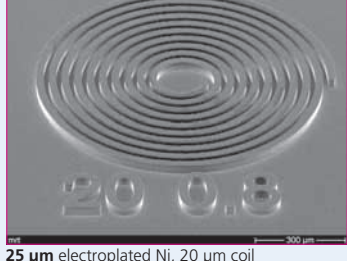
50 µm ma-P 1275 HV



40 µm electroplated Ni



30 µm ma-P 1275 HV, 20 µm coil



25 µm electroplated Ni, 20 µm coil

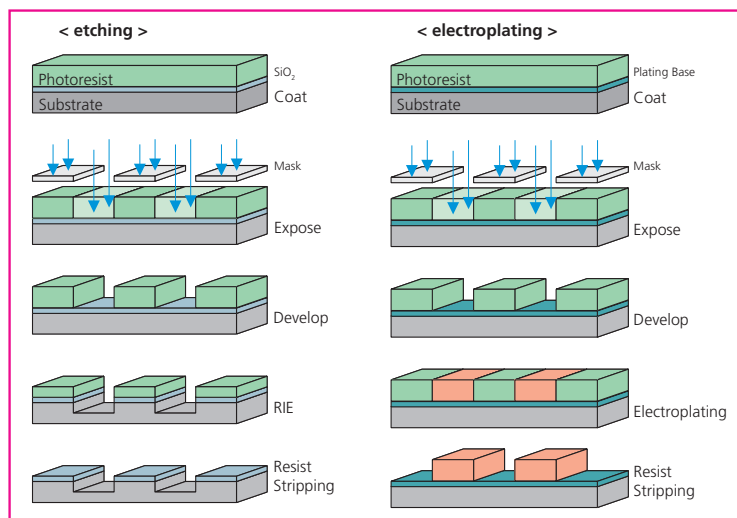
All resist patterns obtained by mask aligner broadband exposure

10.08.02.13.02

Characteristics

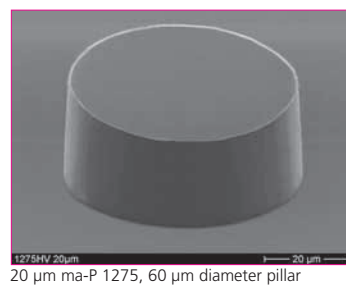
- Specifically designed for electroplating of structures in microsystems technology
- High stability in acid and alkaline plating baths
- Well suitable also for the use as an etch mask exhibiting high dry and wet etch resistance
- Good thermal stability of the resist patterns attainable
- Aqueous alkaline development
- Easy removal
- Side wall angle up to 87° with mask aligner broadband exposure

Process flow

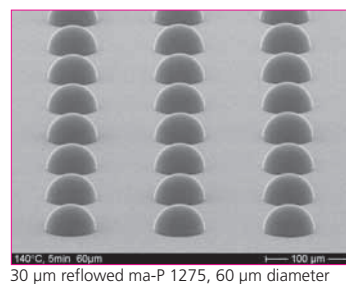


Applications

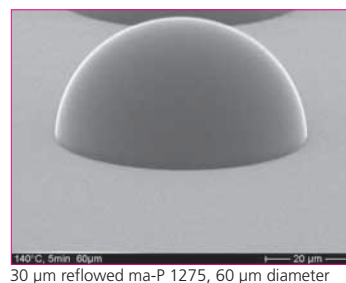
- Mould for electroplating – e.g. for micro coils, micro springs, micro optical components
- Etch mask for metal and semiconductor substrates – e.g. microlenses from reflowed patterns
- Mask for ion implantation



20 µm ma-P 1275, 60 µm diameter pillar



30 µm reflowed ma-P 1275, 60 µm diameter

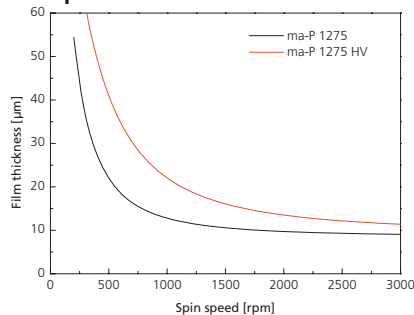


30 µm reflowed ma-P 1275, 60 µm diameter

Film thicknesses

Film thickness	µm	7.5	11	20	30	40	50
ma-P 1275	rpm	3000		500	350	250	–
	s	30		60	60	60	
ma-P 1275 HV	rpm	–	3000	1100	700	500	400
	s		30	60	60	60	60

Spin curves



UV/vis spectra

